

SH Series

Gas Discharge Tubes



Description

The Littelfuse SH Gas Discharge Tubes (GDT) series provides high levels of protection against fast rising transients caused by lightning disturbances. It has a surge rating of 5kA, 8/20 μ s. Offered in a Squared Surface Mount package, which helps to make pick and place on PCB process easier.

This GDT series is perfectly suited for broadband equipment applications. The GDT's low off-state capacitance is compatible with high bandwidth applications and this capacitance loading value does not vary if the voltage across the GDT changes.

The Littelfuse SH Gas Discharge Tube (GDT) series are specifically designed for protection of electrical, multimedia, and communication equipment against over voltage transients in surface mount assembly applications.

Additional Information



Resources




Accessories

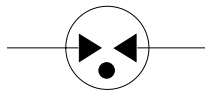


Samples

Agency Approvals

| Agency | Agency File Number |
|---|--------------------|
|  | E128662 |

Two Electrode GDT Graphical Symbol



Features

- Excellent response to fast rising transients
- GHz working frequency
- 5kA, 8/20 μ s surge capability as defined by IEC 61000-4-5 2nd Edition
- UL Recognized
- Offered with squared body package
- Non-Radioactive
- Ultra Low capacitance (<0.7pF)
- Lead-free and RoHS compliant

Applications

- CATV equipment
- Antennas
- RS 485
- Telecom Base Station
- Power Supply AC Main
- G.fast
- EV power Charging
- Inverter/Variable Frequency Drivers (VFDs)
- IEEE 802.3 compliant Ethernet interfaces
- Broad Band equipment
- xDSL, ADSL, ADSL2, VDSL, and VDSL2
- Medical Electronics
- Test Equipment
- General Telecom Equipment
- Renewable Energy

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Electrical Characteristics

| Part Number | Component Specifications (at 25°C) | | | | | | | Life Ratings | | | | | |
|-------------|------------------------------------|-----|-----|------------------------------------|----------|--|-----------------------|---------------------|------------------------------------|-----------------------------------|---------------------------------------|-------------------------------|---------------------------------|
| | DC Breakdown in Volts (@100V/s) | | | Maximum Impulse Break-down Voltage | | Maximum Impulse Discharge Current (8/20µs) | Insulation Resistance | Capacitance (@1MHz) | Impulse Discharge Current (8/20µs) | AC Discharge Current (50Hz, 1sec) | AC Discharge Current (9 Cycles @50Hz) | DC Holdover Voltage (<150ms)* | Impulse Life (10/1000µs) (100A) |
| | MIN | TYP | MAX | @100V/µs | 1000V/µs | 1 Time | MIN | MAX | MAX | MIN | MIN | | MIN |
| SH75 | 60 | 75 | 90 | 600 | 700 | 6kA | 1GΩ @50V | 0.7pf | 10 Shots @ (5kA) | 5A | 15A | 52V | 300 Shots |
| SH90 | 72 | 90 | 108 | 600 | 700 | | 52V | | | | | | |
| SH145 | 116 | 145 | 174 | 600 | 700 | | 52V | | | | | | |
| SH230 | 186 | 230 | 276 | 600 | 700 | | 80V | | | | | | |
| SH250 | 200 | 250 | 300 | 600 | 700 | | 135V | | | | | | |
| SH300 | 240 | 300 | 360 | 650 | 800 | | 135V | | | | | | |
| SH350 | 280 | 350 | 420 | 750 | 900 | | 135V | | | | | | |
| SH400 | 360 | 400 | 480 | 850 | 1000 | | 135V | | | | | | |
| SH470 | 376 | 470 | 564 | 900 | 1100 | | 135V | | | | | | |
| SH600 | 480 | 600 | 720 | 1000 | 1200 | | 135V | | | | | | |

Note:

* Reference REA PE-80, 0.2A, tested to ITU-T Rec K.12 and REA PE 80 <150 ms.
 ** DC spark-over may exceed ± 25% after discharge, but will continue to protect without venting

Product Characteristics

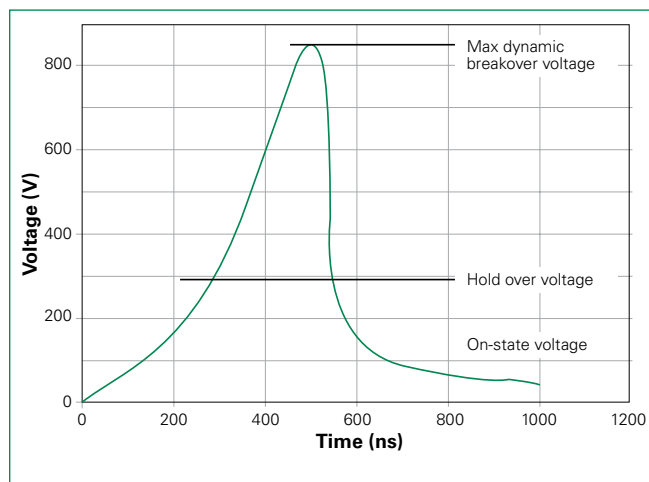
| | |
|--|--|
| Materials | Device Tin Plated 3 -15 Microns Construction: Ceramic Insulator |
| Storage and Operational Temperature | -40 to +90°C |

Typical Insertion Loss

| |
|------------------|
| @1.0GHz = 0.08dB |
| @1.4GHz = 0.16dB |
| @1.8GHz = 0.26dB |
| @2.0GHz = 0.33dB |
| @2.4GHz = 0.47dB |
| @2.8GHz = 0.59dB |
| @3.1GHz = 0.70dB |
| @3.5GHz = 0.89dB |
| @4.0GHz = 1.24dB |

Note: Insertion data for customer reference only, application testing needed for verification.

Voltage Vs. Time Characteristic



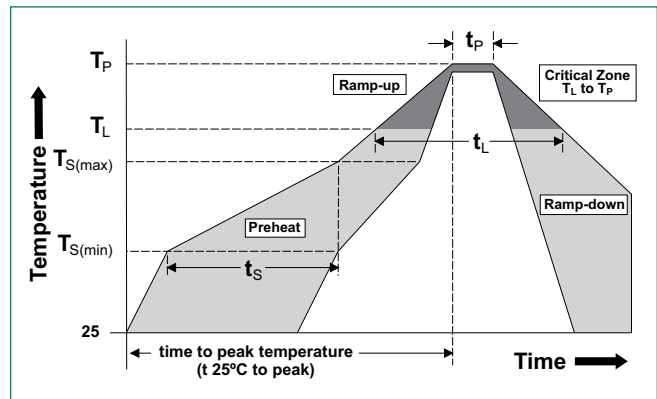
Note: Tested per 1kV/µs waveform

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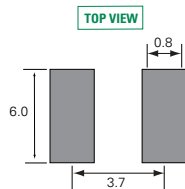
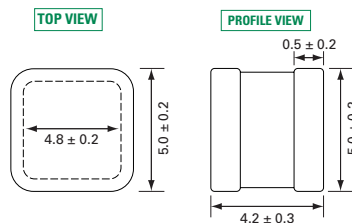
Soldering Parameters - Reflow Soldering (Surface Mount Devices)

| | | |
|--|------------------------------------|-------------------------|
| Reflow Condition | | Pb – Free assembly |
| Pre Heat | - Temperature Min ($T_{s(min)}$) | 150°C |
| | - Temperature Max ($T_{s(max)}$) | 200°C |
| | - Time (Min to Max) (t_p) | 60 – 180 secs |
| Average ramp up rate (Liquidus Temp (T_L) to peak) | | 3°C/second max |
| $T_{s(max)}$ to T_L - Ramp-up Rate | | 5°C/second max |
| Reflow | - Temperature (T_L) (Liquidus) | 217°C |
| | - Temperature (t_L) | 60 – 150 seconds |
| Peak Temperature (T_p) | | 260 ^{+0/-5} °C |
| Time within 5°C of actual peak Temperature (t_p) | | 10 – 30 seconds |
| Ramp-down Rate | | 6°C/second max |
| Time 25°C to peak Temperature (T_p) | | 8 minutes Max. |
| Do not exceed | | 260°C |



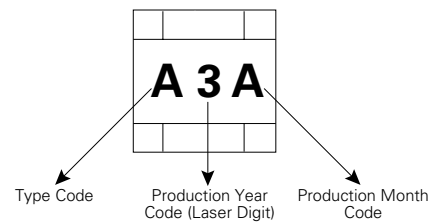
Product Dimensions

Dimensions in millimeters



Recommended Soldering Pad Layout

Product Marking



| Type Code | |
|-----------|-------|
| A | SH75 |
| B | SH90 |
| S | SH145 |
| D | SH230 |
| R | SH250 |
| E | SH300 |
| G | SH350 |
| I | SH400 |
| P | SH470 |
| V | SH600 |

| Month Code | |
|------------|-----------|
| A | January |
| B | February |
| C | March |
| D | April |
| E | May |
| F | June |
| G | July |
| H | August |
| I | September |
| J | October |
| K | November |
| L | December |